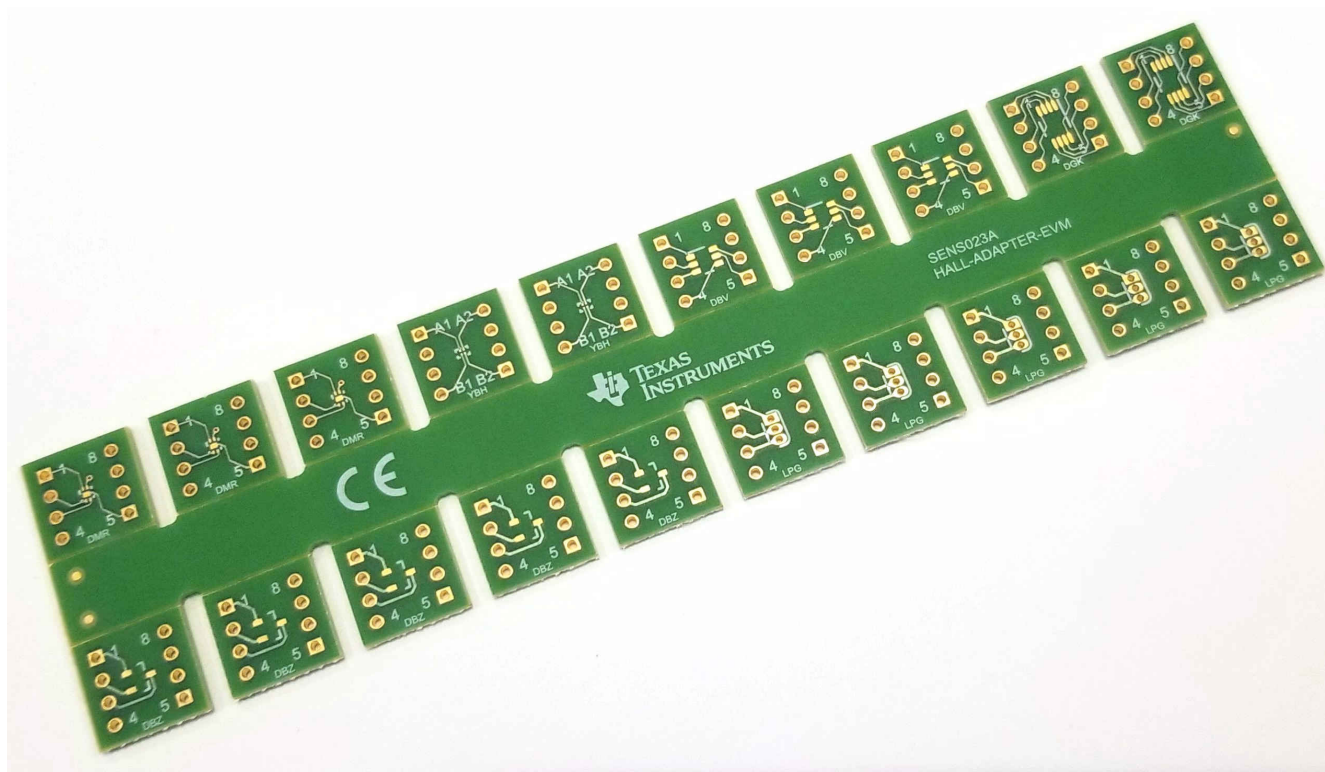


User's Guide
HALL-ADAPTER-EVM

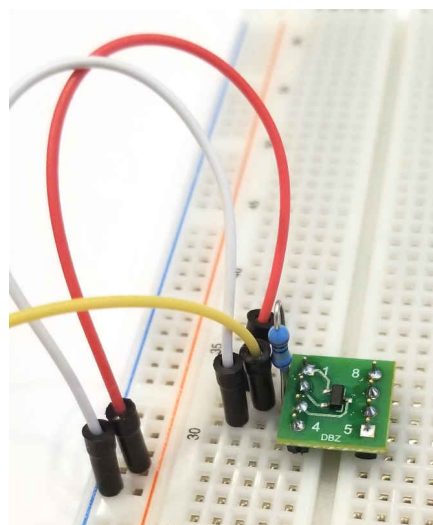


ABSTRACT

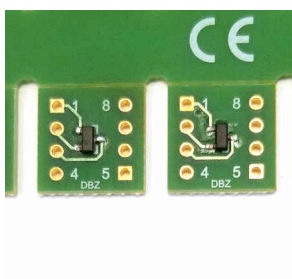


The HALL-ADAPTER-EVM simplifies prototyping SMT ICs:

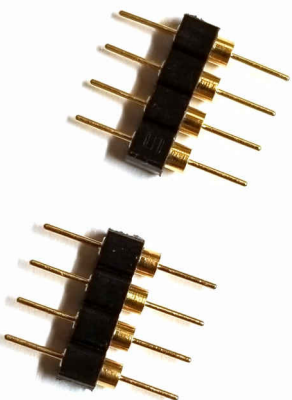
The HALL-ADAPTER-EVM supports SOT23-3 (DBZ), TO-92 (LPG), X2SON (DMR), SOT23-5/6 (DBV), DSBGA (YBH) and MSOP-8 (DGK) packages.



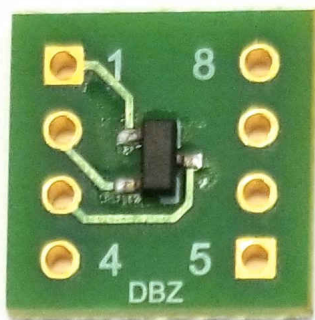
Usage Instructions:



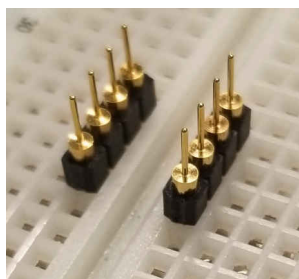
Step 1: Solder IC(s) to adapter PCB. Also solder any necessary decoupling capacitor needed for the device. Refer to the device data sheet for appropriate decoupling capacitor values. ICs may be hand-soldered or attached with IR or hot air reflow techniques.



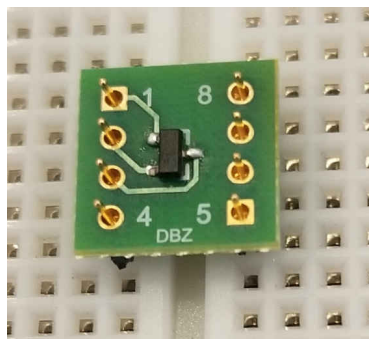
Step 2: Use long nose pliers to snap terminal strips (Samtec part number TSW-124-07-L-S) into 4 position lengths.



Step 3: Gently flex panel at score lines to separate boards.



Step 4: Insert terminal strips into a breadboard or spare DIP socket to align pins.



Step 5: Position board over pins and solder the connections. Carefully remove from breadboard or DIP socket and complete.

1 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (July 2021) to Revision C (October 2021)	Page
• Changed Step 1 of the <i>HALL-ADAPTER-EVM Usage Instructions</i>	1
Changes from Revision A (April 2020) to Revision B (July 2021)	Page
• Updated the numbering format for tables, figures and cross-references throughout the document.....	1
Changes from Revision * (November 2017) to Revision A (April 2020)	Page
• Changed <i>Usage Instructions</i> format to follow other ADAPTER-EVM guides.....	1

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